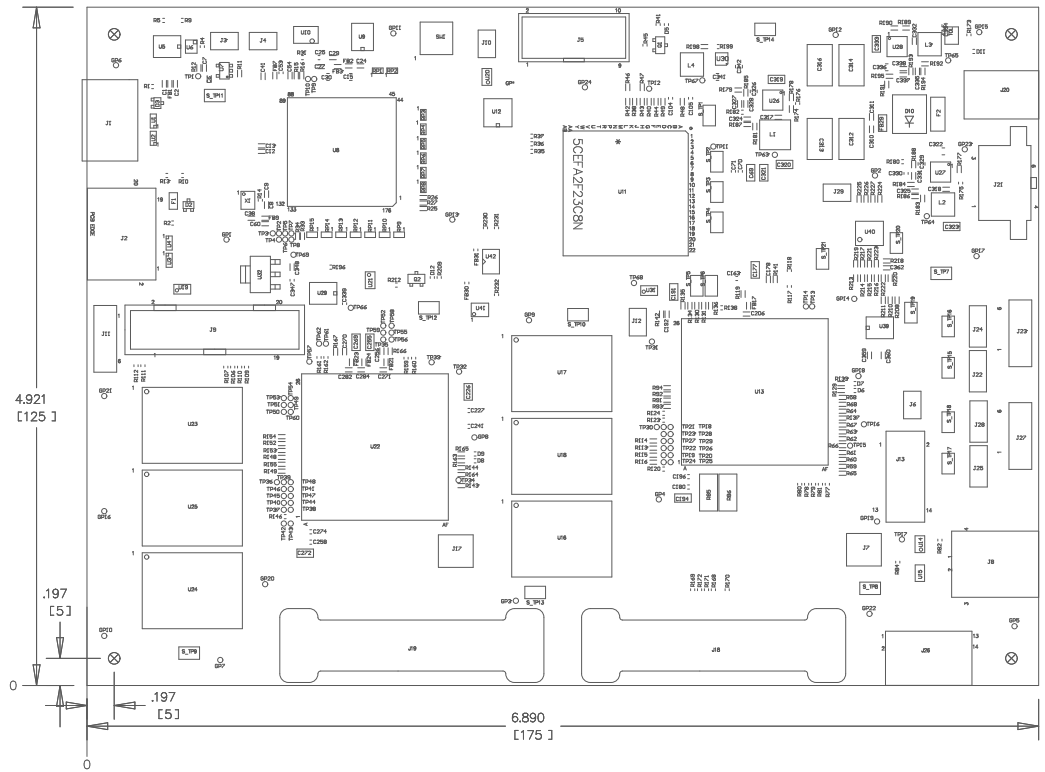


LAYER STACK-UP – ALL DIMENSIONS IN INCHES

		50ohm SINGLE ENDED IMPEDANCE CONTROL +/- 10%	90ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%	100ohm DIFFERENTIAL IMPEDANCE CONTROL +/- 10%
LAYER#	COPPER WEIGHT (OZ)	TRACE WIDTH	TRACE WIDTH / SPACE	TRACE WIDTH / SPACE
LAYER 1 – PRIMARY SIDE – SIGNAL	HALF+PLATING	0.0068	0.0055/0.0055	0.00475/ 0.00725
LAYER 2 – GROUND PLANE	H			
LAYER 3 – SIGNAL	H	0.0057	0.0054/0.0056	0.00475/ 0.00725
LAYER 4 – GROUND PLANE	H			
LAYER 5 – SIGNAL	H	0.0057	0.0054/0.0056	0.00475/ 0.00725
LAYER 6 – GROUND PLANE	H			
LAYER 7 – SPLIT POWER PLANE	H			
LAYER 8 – SPLIT POWER PLANE	H			
LAYER 9 – GROUND PLANE	H			
LAYER 10 –SIGNAL	H	0.0057	0.0054/0.0056	0.00475/ 0.00725
LAYER 11 –GROUND PLANE	H			
LAYER 12 –SIGNAL	H	0.0057	0.0054/0.0056	0.00475/ 0.00725
LAYER 13 –GROUND PLANE	H			
LAYER 14– SECONDARY SIDE – SIGNAL	HALF+PLATING	0.0068	0.0055/0.0055	0.00475/ 0.00725



PRIMARY SIDE VIEW

FAB NOTES:

1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
2. THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
3. BOARD MATERIAL SHALL BE 180 Tg/350 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
4. BOARD MATERIAL & CONSTRUCTION TO BE ULL APPROVED AND MARKED ON THE FINISHED BOARD.
5. MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
6. OVERALL BOARD THICKNESS TO BE .090 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
7. MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
8. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
9. PLATED THROUGH SLOT INDICATED WITH MULTIPLE DRILL HITS SHOULD BE FINISHED AS SMOOTH WALL BY VENDOR.
10. FABRICATOR SHOULD REMOVE ANY UNUSED PADS ON INTERNAL LAYERS.

PROCESS NOTES:

1. EXCEPT AS NOTED BELOW, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, FLASH GOLD PROCESS IS ALSO ACCEPTABLE.
REQUIRED PLATING THICKNESS: NICKEL 150 MICRONS MIN.
GOLD 5-15 MICRONS THK MIN.
2. PLATE ALL THE PAD AREAS OF J18 AND J19, TOP SIDE, WITH A MINIMUM OF 35 AND MAXIMUM 50 MICRO-INCHES OF ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 100 MICRO-INCHES OF ELECTROLYTIC NICKEL.
3. IMPEDANCE INFO IS PROVIDED FOR ALL ROUTING LAYERS BUT SOME LAYERS DO NOT HAVE EVERY LISTED TRACE WIDTH.
4. TRACE WIDTHS WITH NO SPECIFIED IMPEDANCE REQUIREMENT SHOULD BE BUILT TO INDICATED WIDTH.
5. APPLY LPI SOLDERMASK OVER BARE COPPER (SM0BC), COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
6. SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
7. APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

